## NSN 5962-01-233-2299

Memory Microcircuit - Page 1 of 1



View Online at https://aerobasegroup.com/nsn/5962-01-233-2299 **Body Length:** 0.560 inches **Body Width:** 0.458 inches **Body Height:** 0.105 inches **Maximum Power Dissipation Rating:** 770.0 milliwatts **Operating Tempurature Range:** -55.0 to 125.0 degrees celsius Storage Tempurature Range: -65.0 to 150.0 degrees celsius **Features Provided:** Electrostatic sensitive and hermetically sealed and monolithic and erasable and programmable and w/enable **Inclosure Material:** Ceramic **Inclosure Configuration:** Leadless flat pack **Output Logic Form:** N-type metal oxide-semiconductor logic **Input Circuit Pattern:** 24 input **Terminal Surface Treatment:** Solder Voltage Rating And Type Per Characteristic: -1.0 volts power source and 6.0 volts power source **Time Rating Per Chacteristic:** 350.00 nanoseconds propagation delay time, low to high level output and 350.00 nanoseconds propagation delay time, high to low level output **Memory Device Type:** Rom **Test Data Document:** 96906-mil-std-883 standard (includes industry or association standards, individual manufactureer standards, etc.). **Terminal Type And Quantity:** 32 leadless Shelf Life: N/a **Unit Of Measure:** 

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**Demilitarization:** Yes - demil/mli